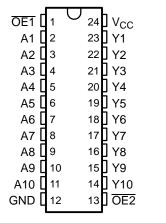


FEATURES

- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.7 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This 10-bit buffer/bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC827A provides a high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that, if either output-enable ($\overline{\text{OE1}}$ or $\overline{\text{OE2}}$) input is high, all ten outputs are in the high-impedance state. The SN74LVC827A provides true data at its outputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T _A	PA	CKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	COIC DW	Tube of 25	SN74LVC827ADW	11/00074	
	SOIC – DW	Reel of 2000	SN74LVC827ADWR	LVC827A	
	SOP - NS	Reel of 2000	SN74LVC827ANSR	LVC827A	
–40°C to 85°C	SSOP - DB	Reel of 2000	SN74LVC827ADBR	LC827A	
-40°C 10 85°C		Tube of 60	SN74LVC827APW		
	TSSOP - PW	Reel of 2000	SN74LVC827APWR	LC827A	
		Reel of 250	SN74LVC827APWT		
	TVSOP - DGV	Reel of 2000	SN74LVC827ADGVR	LC827A	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



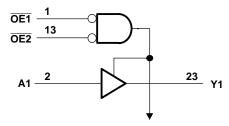
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE

	INPUTS	OUTPUT	
OE1	OE2	Α	Υ
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
X	Н	Χ	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



To Nine Other Channels





Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range, applied to any output in the	high-impedance or power-off state (2)	-0.5	6.5	V
Vo	Voltage range, applied to any output in the	high or low state (2)(3)	-0.5	$V_{CC} + 0.5$	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current		±50	mA	
	Continuous current through V _{CC} or GND			±100	mA
		DB package		63	
		DGV package		86	
θ_{JA}	Package thermal impedance (4)	DW package		46	°C/W
		NS package		65	
		PW package		88	
T _{stg}	Storage temperature range		-65	150	°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
V	Cumply valtage	Operating	1.65	3.6	V	
V _{CC}	Supply voltage	Data retention only	1.5		V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$				
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage	,	0	5.5	V	
\ <i>I</i>	Outrot valtage	High or low state	0	V_{CC}	V	
V_O	Output voltage	3-state	0	5.5	V	
		V _{CC} = 1.65 V		-4		
	High lavel autout august	V _{CC} = 2.3 V		-8	A	
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Law law Law to the standard and	V _{CC} = 2.3 V		8	^	
l _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed. The value of V_{CC} is provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

P/	ARAMETER	TEST C	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT			
		$I_{OH} = -100 \ \mu A$		1.65 V to 3.6 V	V _{CC} - 0.2					
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2					
V		$I_{OH} = -8 \text{ mA}$		2.3 V	1.7			V		
V _{OH}		I _{OH} = -12 mA		2.7 V	2.2			V		
		10H = -12 IIIA		3 V	2.4					
		$I_{OH} = -24 \text{ mA}$		3 V	2.2					
		$I_{OL} = 100 \mu A$		1.65 V to 3.6 V			0.2			
		$I_{OL} = 4 \text{ mA}$		1.65 V			0.45			
V _{OL}	V _{OL}	$I_{OL} = 8 \text{ mA}$	2.3 V			0.7	V			
		I _{OL} = 12 mA	2.7 V			0.4				
		$I_{OL} = 24 \text{ mA}$	3 V			0.55				
I		$V_1 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±5	μΑ		
I _{off}		V_I or $V_O = 5.5 \text{ V}$		0			±10	μΑ		
I_{OZ}		$V_0 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±10	μΑ		
		$V_I = V_{CC}$ or GND	1 - 0	3.6 V			10			
I _{CC}		$3.6 \text{ V} \le V_1 \le 5.5 \text{ V}^{(2)}$	$I_{O} = 0$	3.0 V		10		μΑ		
ΔI_{CC}		One input at V _{CC} – 0.6 V,	Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500	μΑ		
C _i	Control inputs	V = V or GND	3.3 V	5			pF			
O _i	Data inputs	$V_I = V_{CC}$ or GND	3.3 V		4		þΓ			
Co	·	$V_O = V_{CC}$ or GND		3.3 V		7		pF		

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This applies in the disabled state only.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V_{CC} = 2.5 V \pm 0.2 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V		UNIT
(INPU	(INFOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y	(1)	(1)	(1)	(1)		7.1	1	6.7	ns
t _{en}	ŌĒ	Y	(1)	(1)	(1)	(1)		8.5	1	7.3	ns
t _{dis}	ŌĒ	Y	(1)	(1)	(1)	(1)		7.3	1.8	6.7	ns
t _{sk(o)}										1	ns

⁽¹⁾ This information was not available at the time of publication.

Operating Characteristics

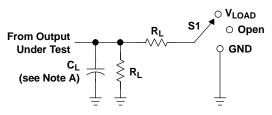
 $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
Power dissipation capacitance		Outputs enabled	f = 10 MHz	(1)	(1)	24	ρF
C_{pd}	per buffer/driver	Outputs disabled	I = IU MHZ	(1)	(1)	5	pΕ

⁽¹⁾ This information was not available at the time of publication.



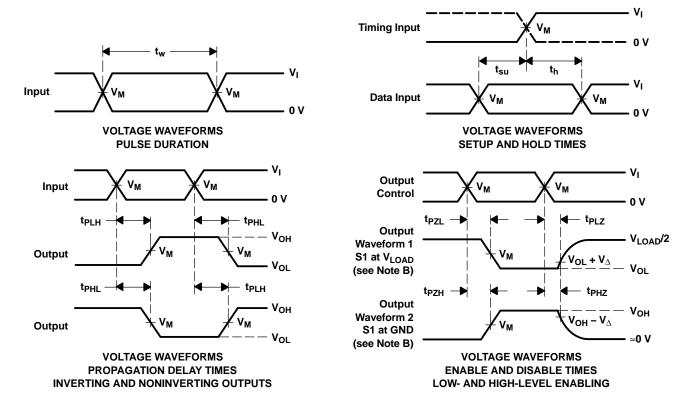
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

.,	INPUTS		.,	.,		_	.,	
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	${f V}_{\Delta}$	
1.8 V \pm 0.15 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V	
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V	
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V	
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V	



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





com 4-Jun-2007

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finisl	h MSL Peak Temp ⁽³⁾
SN74LVC827ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74LVC827ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADGVR	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADGVRE4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADGVRG4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827ANSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI
SN74LVC827APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWT	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWTE4	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC827APWTG4	ACTIVE	TSSOP	PW	24	250	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

4-Jun-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
					no Sb/Br)		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

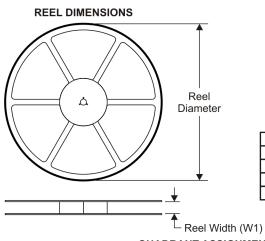
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

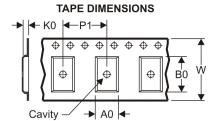
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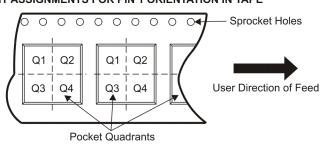
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC827ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74LVC827ADGVR	TVSOP	DGV	24	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LVC827ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74LVC827ANSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1
SN74LVC827APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC827ADBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74LVC827ADGVR	TVSOP	DGV	24	2000	346.0	346.0	29.0
SN74LVC827ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74LVC827ANSR	SO	NS	24	2000	346.0	346.0	41.0
SN74LVC827APWR	TSSOP	PW	24	2000	346.0	346.0	33.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

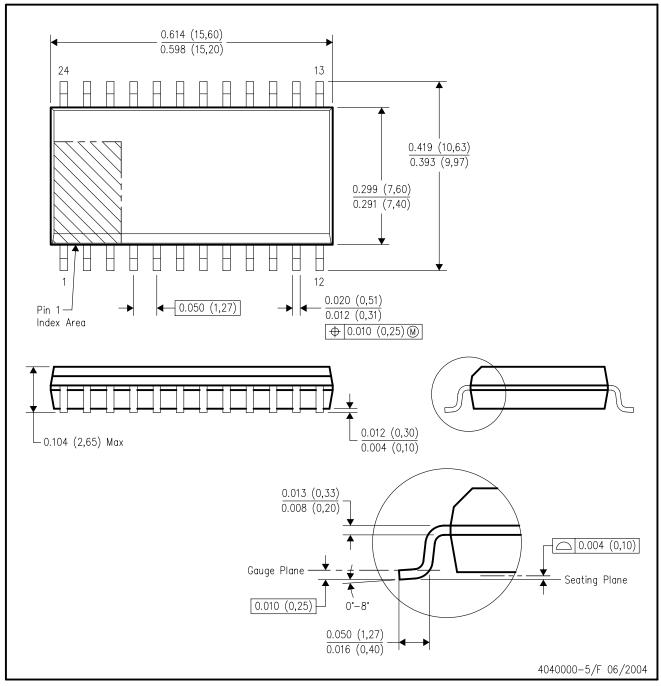
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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